

/ Revised record

A	2020-5-25	ALL			
B	2022-6-28	3	Fig.1 Fig.2	 S00123-S-BAT54W-0 .2A30V-A.pdf	

/ Descriptions

SOD-123

Schottky Diode in a SOD-123 Plastic Package.

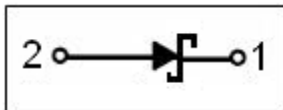
/ Features

Metal silicon junction, majority carrier conduction. Guarding for overvoltage protection.Low power loss, high efficiency. High current capability. low forward voltage drop. High surge capability. For use in low voltage, high frequency inverters,free wheeling, and polarity protection applications.HF Product.

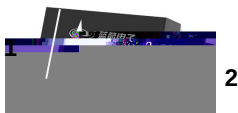
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN1:Cathode

PIN2:Anode

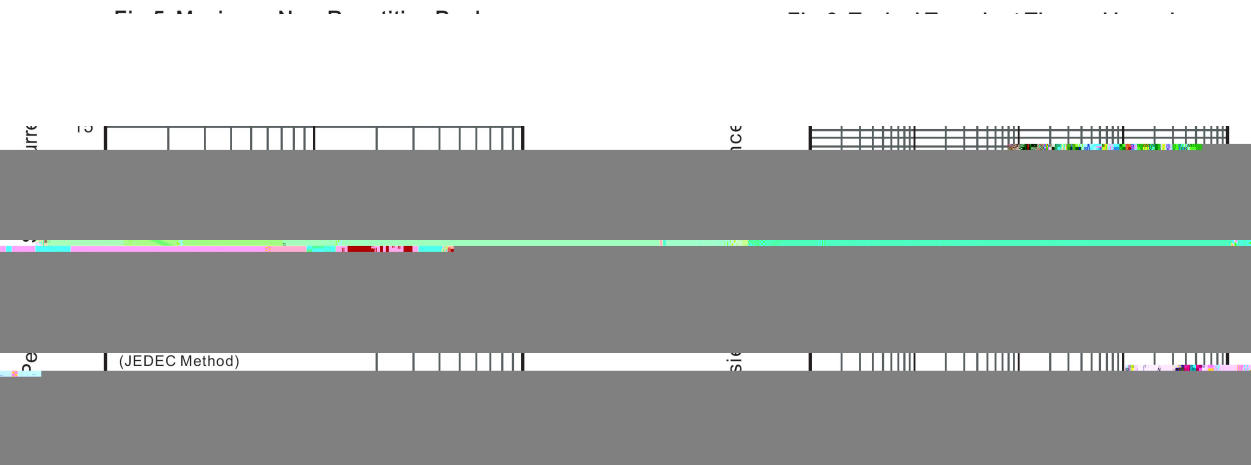
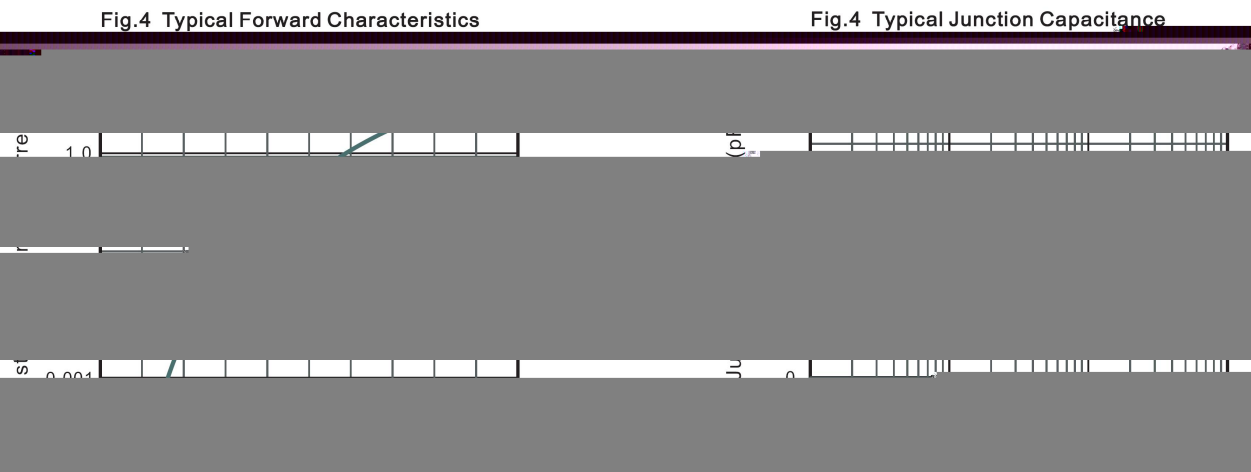
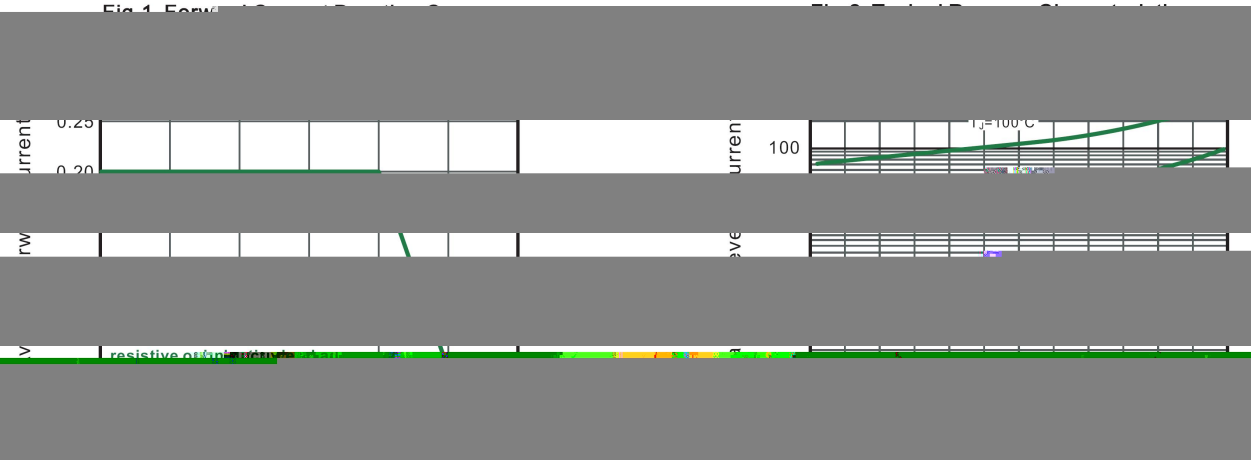
/ Marking

Type number	Marking code
BAT54W	L4

Parameter	Unit
Peak Repetitive Reverse Voltage	V
Maximum Average Forward Current	A
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated current (JEDEC method)	A
Typical Thermal Resistance	C/W
Typical Junction Capacitance at VR=0V, f=1MHz	pF
Junction and Storage Temperature	°C
Parameter	Unit

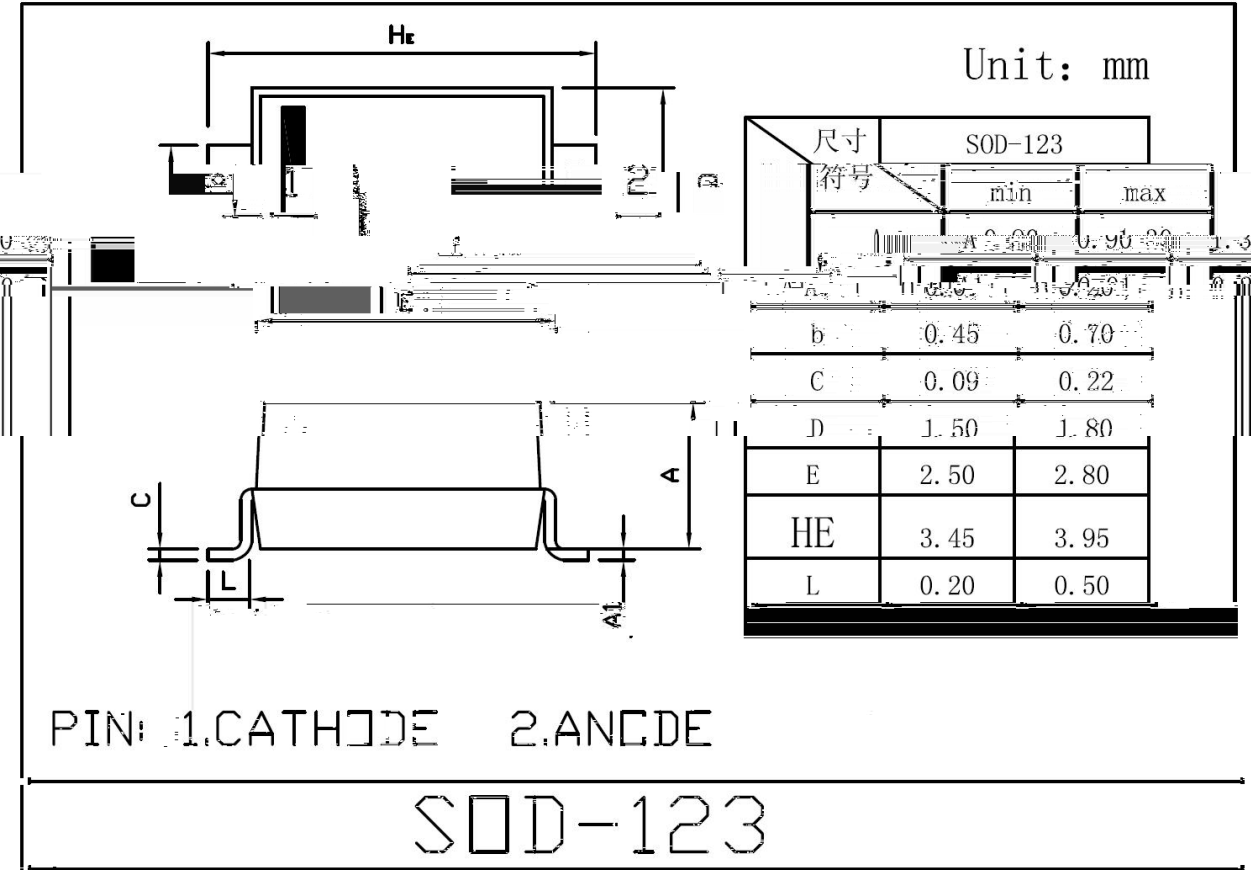
Maximum Instantaneous Forward Voltage V_F $I_F=0.001A$ 0.32 V

/ Electrical Characteristic Curve





/ Package Dimensions



/ Marking Instructions

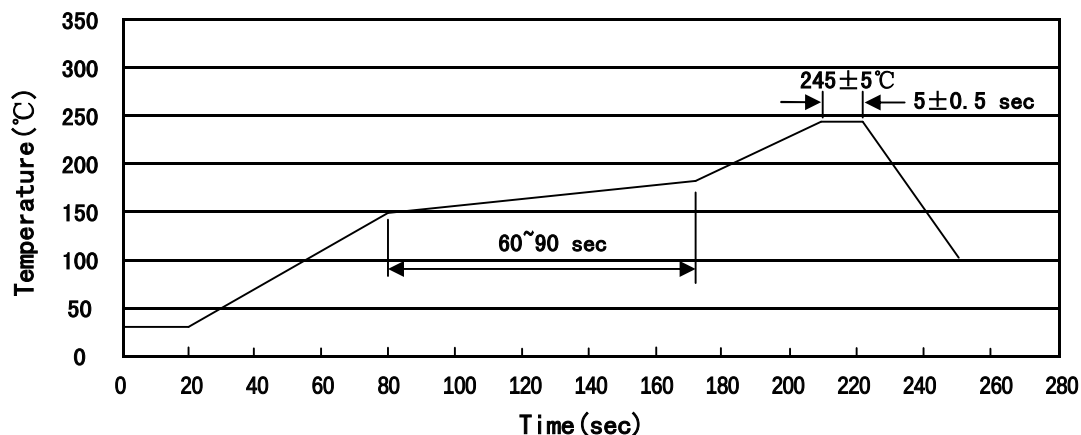


L4

Note:

L4 : Product Type

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180°C, Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | | 2 | 10°C/sec. | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box	Outer Box
SOD-123	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices